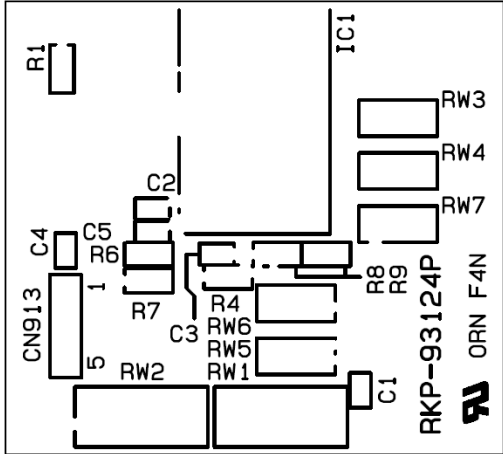
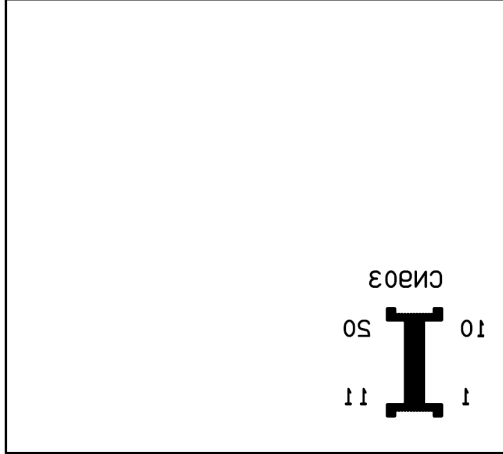


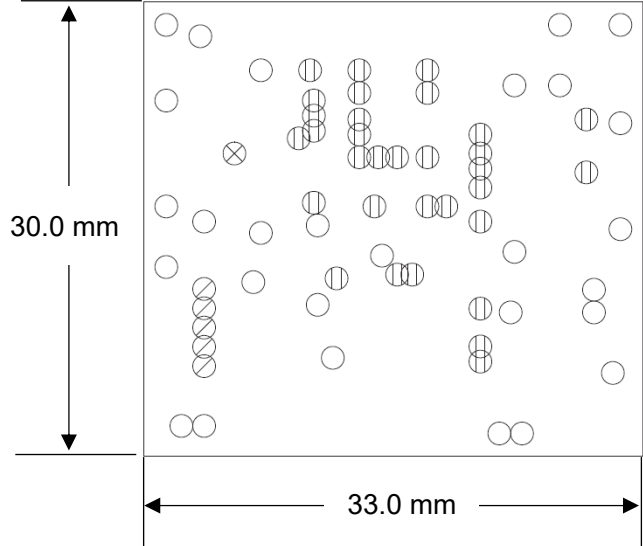
SILK PRINT FOR PARTS SIDE



SILK PRINT FOR SOLDERING SIDE

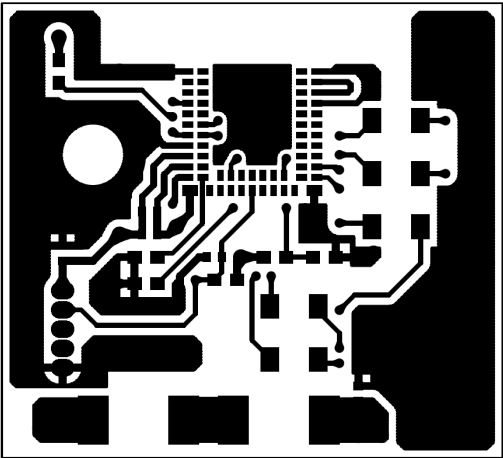


THROUGH HOLE FOR PARTS SIDE

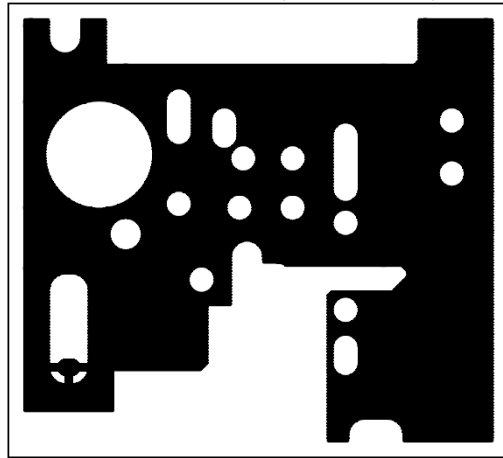


MARK	DIAGRAM	HOLE	MEMO
⊙	φ 0.3	TH	
○	φ 0.5	TH	
⊗	φ 0.85	TH	
⊗	φ 3	NTH	

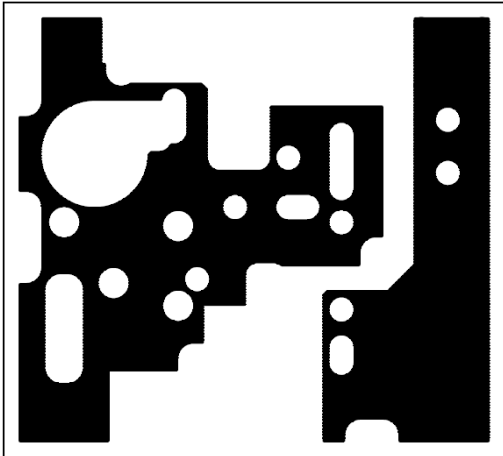
PARTS SIDE



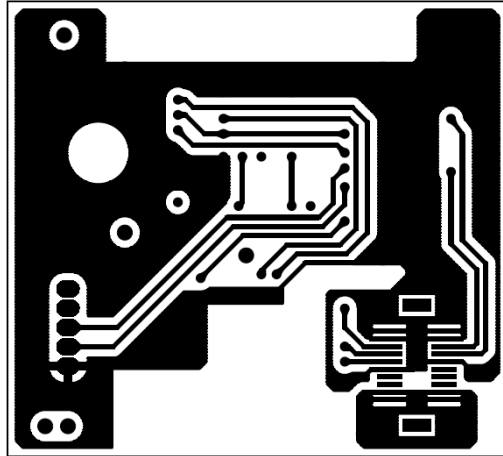
INNER LAYER (2nd LAYER)



INNER LAYER (3rd LAYER)



SOLDERING SIDE



SPECIFICATION FOR PCB

- ・PCB No. : RKP-93124P
- ・Material : Glass epoxy
- ・Thickness : 1.6mm
- ・Layer number : 4
- ・Thickness copper film : Surface 35um, Inner 35um
- ・Copper thickness of the via's : 35um above.
- ・Minimum conductor width : 0.3mm
- ・CTI : 100 above

All drawings are view of parts side

SCALE 2:1

注 記 NOTES		改版担当者 REV. BY	改版日 REVISED	名 称 NAME BLE PCB
改版回数 REV. 0	総頁数 PAGES 1			EAGLE3
承 認 APPROVED 山田和則	検 討 CHECKED 小野圭	製 図 DRAWN 木村司	作成日 DATE 2024.2.21	図 番 DWG. NO. E 3 - 6 9 9 1 - 6 5 1 8 - 1 0 - 0 1 A